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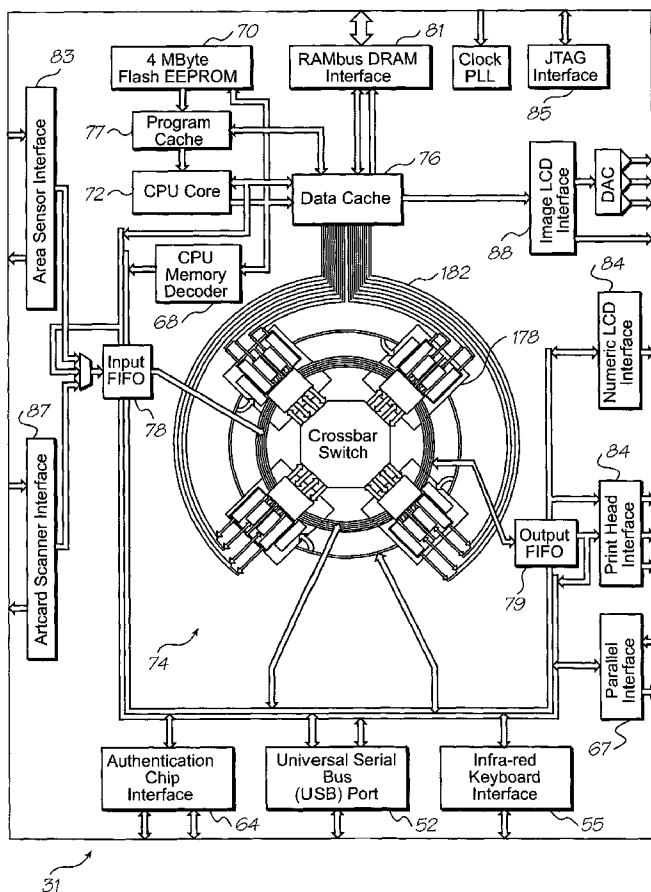
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(54) Title: IMAGE SENSING APPARATUS INCLUDING A MICROCONTROLLER



(57) Abstract: An image sensing and processing apparatus includes an image sensor that is capable of generating signals carrying data relating to an image sensed by the image sensor. The apparatus includes a microcontroller. The microcontroller includes a wafer substrate. VLIW processor circuitry is positioned on the wafer substrate. Image sensor interface circuitry is positioned on the wafer substrate and is connected between the VLIW processor circuitry and the image sensor. The image sensor interface circuitry is configured to facilitate communication between the VLIW processor circuitry and the image sensor. Bus interface circuitry that is discrete from the image sensor interface circuitry is connected to the VLIW processor circuitry so that the VLIW processor circuitry can communicate with devices other than the image sensor via a bus.



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